

CHEMICALLY-AMPLIFIED POSITIVE PHOTSENSITIVE RESIN
COMPOSITION, MANUFACTURING METHOD OF SUBSTRATE WITH
CASTING MOLD, AND MANUFACTURING METHOD OF ELECTROPLATED
MOLDED ARTICLE

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ABSTRACT OF THE DISCLOSURE

A chemically-amplified positive photosensitive resin composition with excellent sensitivity and rectangularity, a manufacturing method of a substrate with a casting mold, and a manufacturing method of an electroplated molded article are provided.

10 The chemically-amplified type positive photosensitive resin composition contains a resin (A) containing an acid-dissociated protecting group and obtained by polymerizing a mixture, a novolac resin (B), a photoacid generator (C), and a solvent(D). The novolac resin (B) includes a high-ortho novolac resin (B-1) having 18% to 25% of a methylene group bonded in an ortho-ortho arrangement.

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Fig. 1